



#14/AMC+BAF 881

ATTENTION: BOX AFTER FINAL RESPONSE UNDER 37 C.F.R. § 1.118 EXPEDITED PROCEDURE REQUESTED EXAMINING GROUP 28.17

PATENT

Customer No. 22,852

Attorney Docket No. 08038.0024

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re A	Application of:)			•
Noriaki FUKIAGE))) Group Art Unit: 28	11		
Serial No.: 09/657,055))) Examiner: H. Vu			
Filed:	September 7, 2000))	TECH		
For:	SEMICONDUCTOR DEVICE HAVING MULTILAYER INTERCONNECTION STRUCTURE AND METHOD OF MAKING THE SAME))))	LECHMOLOCA CEMLER	NOV 29 2002	RECEIVED
Assistant Commissioner for Patents Washington, DC 20231			R 2800	<i>⊱</i> ->)

<u>AMENDMENT</u>

In reply to the Final Office Action of August 26, 2002, and pursuant to 37 C.F.R. § 1.116, Applicant proposes that this application be amended as follows:

IN THE CLAIMS:

Sir:

Please cancel claim 14 without prejudice or disclaimer, and amend claims 1, 5, and 15, as follows:

FINNEGAN
HENDERSON
FARABOW
GARRETT&
DUNNER LLP

1300 I Street, NW Washington, DC 20005 202.408.4000 Fax 202.408.4400 www.finnegan.com 1. (Twice Amended) A semiconductor device comprising:

an insulator film formed on a substrate;

a wiring layer of copper formed proximate the insulator film; and